



# ISES MEMBERSHIP BENEFITS

BE PART OF THE WORLDS LEADING SEMICONDUCTOR ASSOCIATION  
DEDICATED EXCLUSIVELY TO END USERS, FOUNDRIES, IC DESIGN,  
IDM'S, OSATS & RESEARCH INSTITUTE LEADERS



● CONTACT US

[INFO@ISESGLOBAL.COM](mailto:INFO@ISESGLOBAL.COM)

# ABOUT US

## ISES Mission

The International Semiconductor Executive Summits (ISES) is where **leaders connect** with the end goal to **collaborate** and share ideas in a trusted network to establish an effective global semiconductor ecosystem. We provide a unique platform which entails collaboration through global leading executives connecting with peers, partners, and customers to connect ideas share best practices, identify challenges and gain visibility across the global semiconductor industry.



## Leadership

ISES is led by an Advisory Board and a set of subsidiary **Task Forces**. These Advisory Board of Directors consist of semiconductor industry executives from acclaimed companies including **Intel, TSMC, Broadcom, MediaTek, Infineon, Vanguard, Ams Osram, Amkor** and many other global leaders who collaborate to support our mission.

## Global Executive Network

ISES hosts the highest NPS rating Semiconductor Summits in the World. With a capped audience of 150 leaders in each major region: USA, Europe, Taiwan & China consisting of Participation of Leaders in **Technology, Manufacturing, Operations and R&D**.

## Visibility, Intelligence & Events

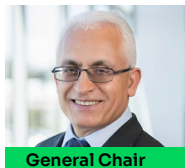
With absolute leverage of the above, ISES provides its members a platform for collaboration and strategic thought leadership through our hybrid **regional and global events**, dedicated to Advanced Packaging, Memory Manufacturing, Automotive Semiconductors, Power Semiconductors, Market Research and more. Covering strategic technical discussion alongside a commitment to Inclusion & Diversity & Workforce Development initiatives, & a variety of **marketing communications and visibility opportunities**.





INTERNATIONAL  
SEMICONDUCTOR  
EXECUTIVE SUMMITS

# ISES Advisory Board Members



**General Chair**  
**Hamid Azimi**

Corporate VP, Director of  
Substrate Packaging TD



**Deputy General**  
**Markus Keil**

VP Global Operations and Member of  
Executive Board



**Sunil Banwari**

COO



**Xiaoning Qi**

CEO



**Jennifer Zhao**

GM & EVP for Advanced Optical  
Sensors Division



**Vincent Dicaprio**

VP Advanced Packaging and ICAPS  
/ Head of Business and Corporate  
Development



**Bernard Lim**

Vice President Global  
Operations



**CJ Hsieh**

COO



**Xiaoxin Qiu**

CEO



**Mart Weigert**

VP & GM Industrial Fiber  
Products Division



**Ralf Bornefeld**

SVP, Power Semiconductors  
& Modules



**YuanYuan Zhou**

Global Business Director



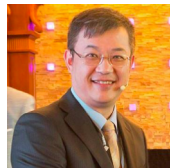
**Amy Leong**

CNO



**Qingchun Zhang**

Professor



**Andy Chuang**

VP Business Development



**J Philip Vincent**

Group Director



**Farhat Jahangir**

CEO and Co-Founder



**Vance Wang**

Formerly VP New Fab Project  
at GTA



**Chang Fu**

Advanced Module R&D Dep.,  
Deputy Director



**Denis Marcon**

General Manager



**AK Chong**

intel



**Dato' Seri Lee  
Kah Choon**

Special Investment  
Advisor to Chief Minister  
of Penang



**Shih-Chieh Chang**

General Director, Electronic  
and Optoelectronic System  
Research Laboratories



**Christine Dunbar**

Senior VP Global Sales



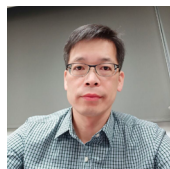
**Yaojian Lin**

VP, GM of Technology R&D  
Center



**Oreste Donzella**

EVP of Electronics, Packaging  
and Components



**Ian Hsu**

Director IC Packaging  
Technology Development



**Ryan Chen**

General Manager of Computing  
and AI Technology Group



**Akshay Singh**

VP, Advanced Packaging  
Technology Development



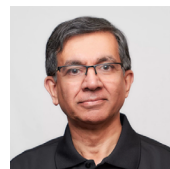
**Thy Tran**

VP DRAM Process Integration



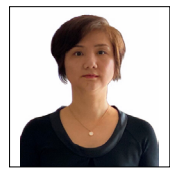
**Jy Zhang**

Chairman & CEO



**Naveed Sherwani**

Chairman Of Osfpga Foundation  
Chairman & Coo of Rapid Silicon



**Jian Zhang**

VP Product Test Engineering



**Edward Wei**

Senior Adviser to President



**Shu-Ming Liu**

VP



**Luba Tang**

Founder & CEO



**Tim Yeh**

Technical Director of Power BU



**Eric Lee**

President of Sales Group



**Joseph Chou**

GM



**Yongxiang Wen**

Process Technology Director



**Yu-po Wang**

VP Corporate R&D Center



**Andrew Peng**

Formerly VP BD Greater  
China at Spin Memory



**Jason Zee**

Global Vice President, General  
Manager of the Storage and System  
Level Test Group at Teradyne,  
China Managing Director



**Key Chung**

Advanced Packaging CTO



**Primit Parikh**

Co-founder, President & COO



**YC Lee**

CEO



**Chris Chern**

Director, Manufacturing  
Technology Center



**Kam Lee**

Senior Director, Deputy Head  
of TSMC Advanced Packaging  
Technology and Service



**Shaojun Wei**

Professor



**Yens Ho**

R&D Director



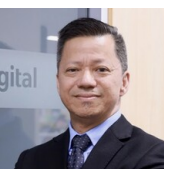
**Wei Wang**

Assistant President; Director  
of Strategy Development



**Geoffrey Stoddart**

Commercial Director



**KL Bock**

SVP Global Flash Backend  
Operations



**LW Yong**

Head of R&D, Power  
Modules in Asia



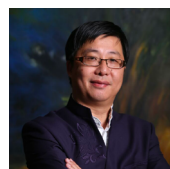
**Weihua Cheng**

COO



**Santosh Kumar**

Director & Principal Analyst



**Wei Li**

Chairman



**Tianchun Ye**

Secretary General of China Integrated  
Circuit Innovation Alliance  
Academician of the International  
Eurasian Academy of Sciences  
President of IC branch of China





# • ISES Power Advisory Board Members



**RALF BORNEFELD**

SVP, Power  
Semiconductors &  
Modules



**ALEX LIDOW**

CEO



**JIM WITHAM**

CEO



**RAINER KAESMAIER**

Managing Director,  
Semiconductors



**DENIS MARCON**

General Manager



**MARCO GIANDALIA**

VP IC Design



**CARLOS CASTR**

VP & GM Power GaN FETs



**AVINASH KASHYAP**

VP Power Technology



**EDOARDO MERLI**

Executive Vice President, Power  
Transistor Sub-Group Automotive  
and Discrete Group



**CHRISTOPHE MALEVILLE**

CTO



**PRIMIT PARIKH**

Co-founder, President &  
COO



**AGNES JAHNKE**

Product Marketing  
Manager SiC and GaN





# WHY MEMBERSHIP?



## ● WHY MEMBERSHIP?

Traditionally ISES has been funded through supplier sponsorship, allowing our IC Design, Foundry, IDM, End User & OSAT partners to attend free of charge. However, as we continue to grow as a platform by expanding to new regions such as Southeast Asia & the Middle East, whilst delivering the best-in-class speakers and venues we can no longer rely on supplier sponsorship alone.

Moreover, for us to continue to deliver and expand our events to you at this elite level, we will be introducing a low-cost Membership model for each IC Design, IDM, Foundry, End User, OSAT & Research Institution who wishes to participate at our events. The following pages will summarise the key benefits and pricing of the membership package for your company.







INTERNATIONAL  
SEMICONDUCTOR  
EXECUTIVE SUMMITS



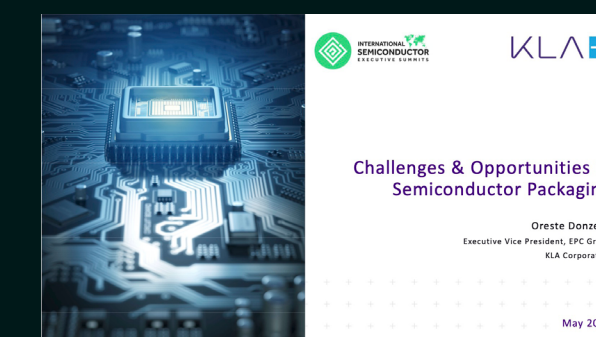
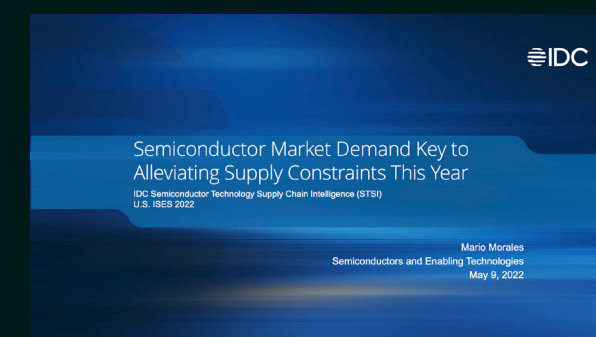
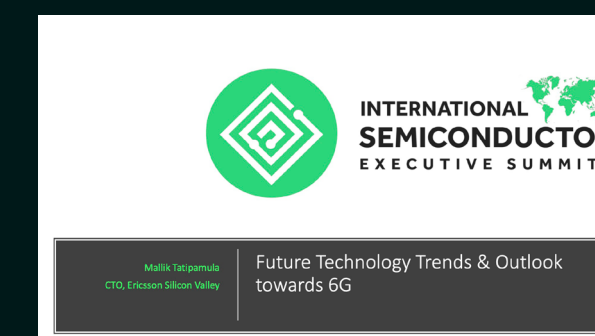
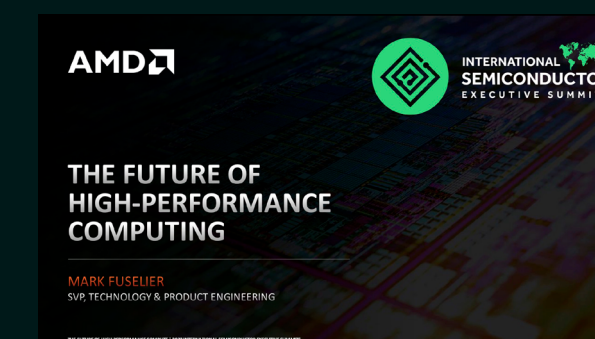
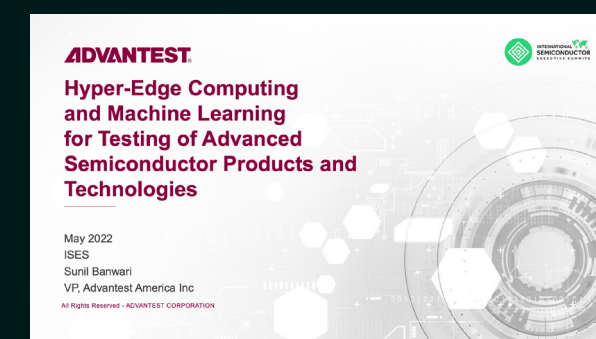
MEMBERSHIP

Reports

# 1 • YEAR ROUND ACCESS TO ALL ISES 2023 PRESENTATIONS & VIDEO RECORDINGS

ISES Members have access to technology presentations, market reports and our exclusive, specially curated, ISES Presentations and Market Updates as of their membership benefits. All of these Presentations and Market Updates provide information that can be used for corporate strategy, new product development, innovation, research, technology development or marketing. ISES Staff is glad to assist you access all information.

[WWW.ISESGLOBAL.COM](http://WWW.ISESGLOBAL.COM)





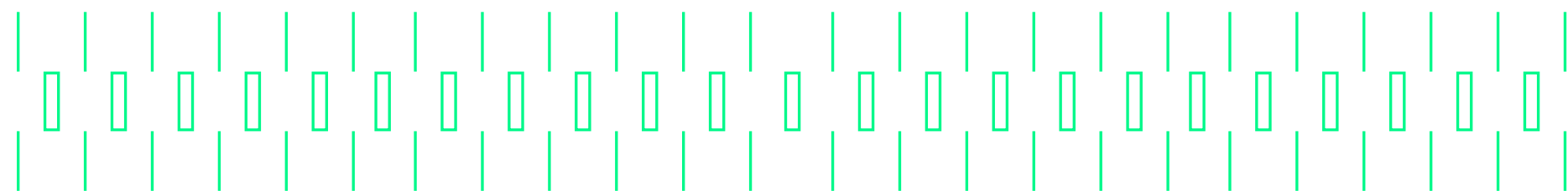
# 2 • ACCESS TO THE GLOBAL ISES NETWORK



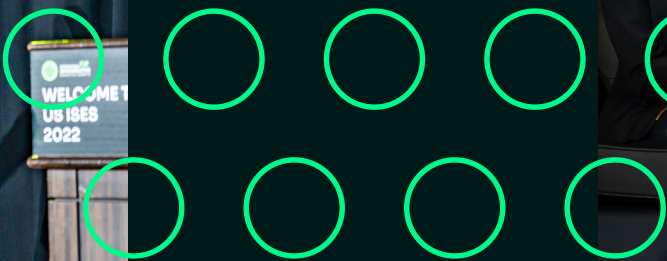
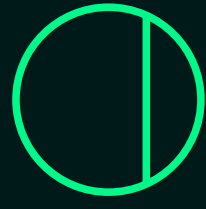
ISES strengthens the connections among its members through our Executive Summits. Designed to meet & discuss challenges and opportunities, and to explore collaboration possibilities. ISES events are by-invitation-only to ensure a relevant audience and highly selective to ensure effective networking. Upon registering our ISES annual Membership, your company will gain market intelligence, brand visibility and discounted member rate | person access to the following ISES 2023 events:

▪ ISES Middle East	22-23	February	Oman
▪ ISES USA	07-08	March	USA
▪ ISES Taiwan	09-10	May	Taiwan
▪ ISES EU Power	14-15	September	Italy
▪ ISES China	17-18	October	China
▪ ISES SEA	14	November	Malaysia

View upcoming events on: [WWW.ISESGLOBAL.COM](http://WWW.ISESGLOBAL.COM)









### 3 . PROMOTION & VISIBILITY FOR YOUR COMPANY



INTERNATIONAL  
**SEMICONDUCTOR**  
EXECUTIVE SUMMITS

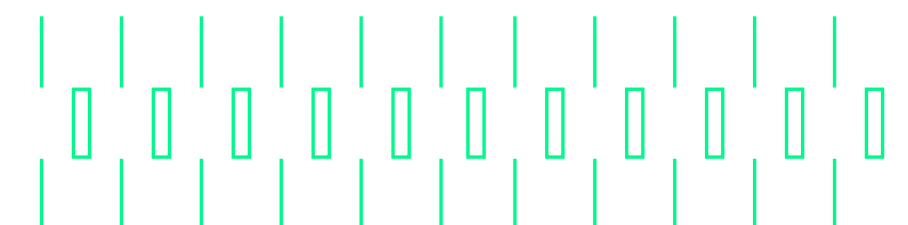


MEMBERSHIP

Promotion

**ISES is proud to promote its members. We offer a wide range of services to create more visibility for your company**

- Member Product Release via our Mailing List of 10,000+ subscribers
- Media Visibility – We will include your company logo in all general ISES flyer promotions to our 21,000+ followers on LinkedIn Community, plus our event website. We will also include your company logo and ‘about us and company contact info in all ISES event digital program brochure to be accessed on our event apps.
- Member Video Interviews: We will give your In-person event representative the chance to deliver a testimonial with digital logo placement as part of our event video trailers which will be released via mail blast and LinkedIn post after each event.
- Member News – Send us your news and we will share your innovations with our network through social media.
- Sponsorship & Event Participation Opportunities – We offer a special 10% discount on sponsorship packages as an exclusive benefit to our members to increase your company’s visibility at our activities and events



# 3 . PROMOTION & VISIBILITY FOR YOUR COMPANY

## REGIONS COVERED

USA  
Taiwan  
Europe  
Middle East  
China



## TOPICS COVERED

### ISES USA/TAIWAN/CHINA

- Advanced Packaging
- AI
- Chiplets
- High Performance Computers (HPC)
- Memory Manufacturing
- Supply Chain
- 5G/6G

### POWER SEMICONDUCTOR

- Automotive
- GaN
- SiC
- Supply Chain
- Renewable Energy

### ISES OMAN

- Design Verification
- MEMS & Sensors
- Power Semi

### ISES SEA

- Advanced Packaging
- Assembly & Test
- Supply Chain



INTERNATIONAL  
**SEMICONDUCTOR**  
EXECUTIVE SUMMITS



MEMBERSHIP

Promotion

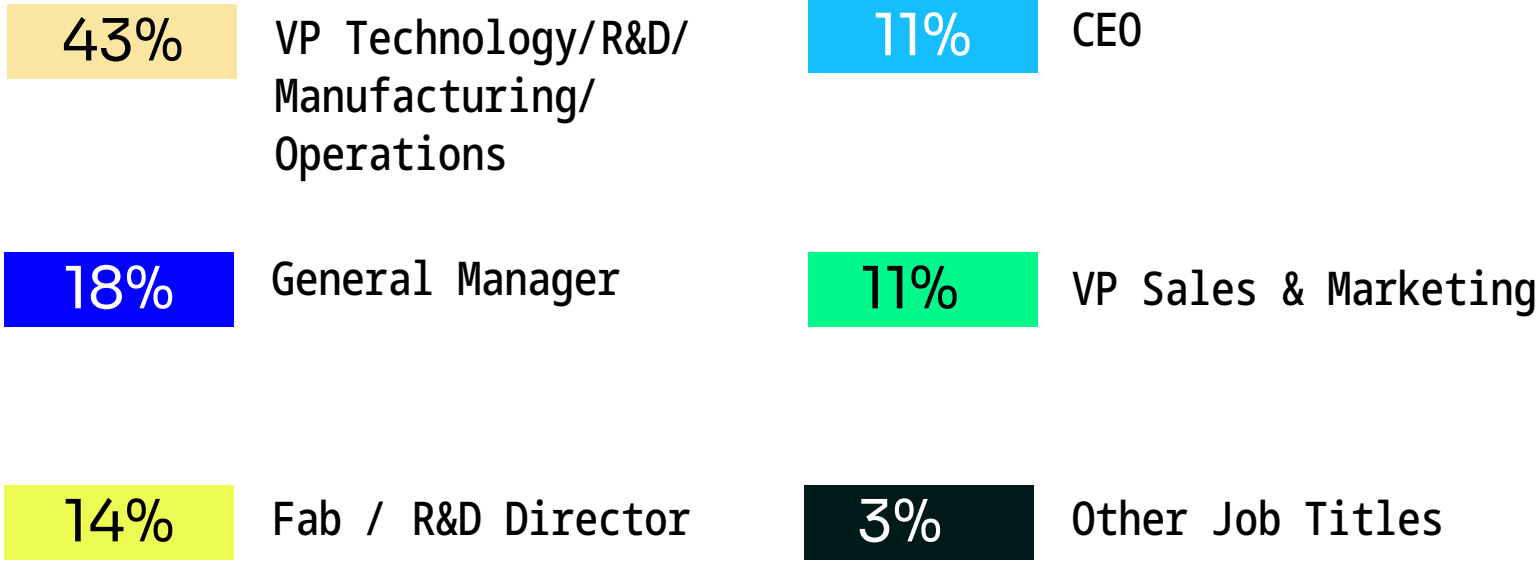
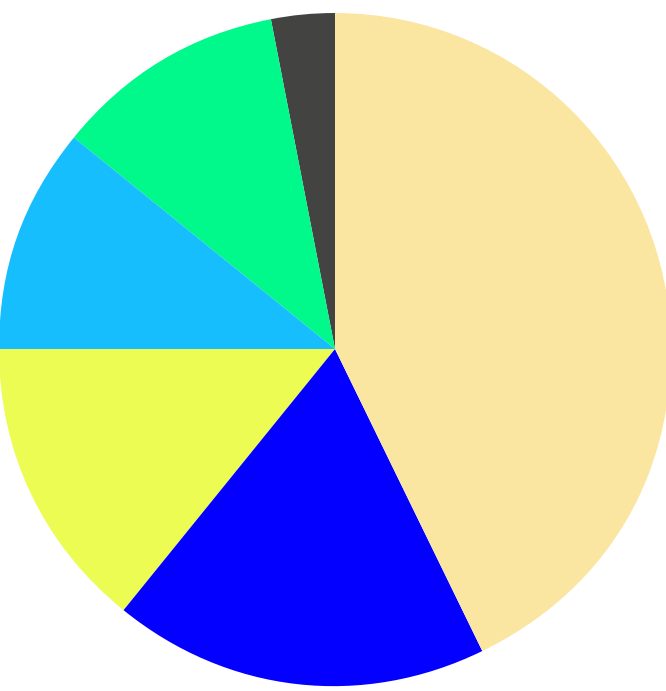
## FACTS & FIGURES

778	Attendees
150	Thought Leaders Presentations
72+	Hours of Networking
360	Business Meetings Pre-Arranged
21,000+	Follower on LinkedIn
132	IDM/Foundry (Fabs) Companies in Attendance
29	OSAT Companies in Attendance
157	Fabless Companies in Attendance
61	End User Companies (Automotive/Mobile Phone/Data Servers and etc) in Attendance
62	Equipment & Materials Manufacturing Companies in Attendance



# 3 . PROMOTION & VISIBILITY FOR YOUR COMPANY

## JOB TITLE BREAKDOWN



MEMBERSHIP

Promotion

## COMPANY PROFILES

IC Design Houses

IDMs

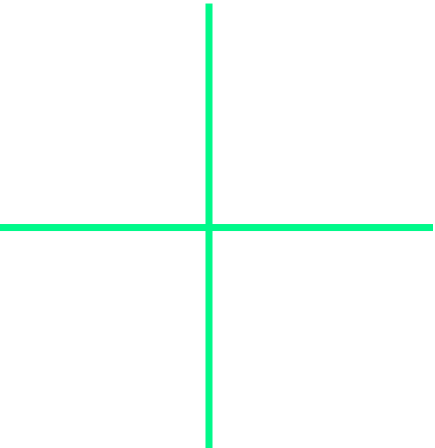
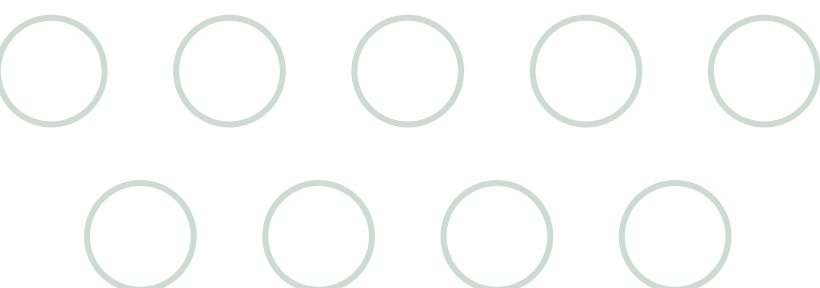
Foundries

Research Institutes

OSATs

Semiconductor Equipment & Materials Manufacturers

End User: Automotive, Communications, computing, healthcare, transportation, clean energy, and others)



## 4 • BECOME A MEMBER

Each of our End User, IC Design, IDM, Foundry, OSAT & Research Institute partners will be allowed to register one annual membership package for the year, which will include 1 VIP attendee pass to ALL ISES 2023 events for C/GM/VP & Director leadership executives.

This will be in addition to the following benefits below:

### MEMBER BENEFITS SUMMARY

- All additional event passes will be registered at the lower member rate (please see example on next page)
- First refusal to available speaker slots (subject to Advisory Board approval)
- Access to all ISES members portal which includes exclusive access to all event presentation slides & video recordings
- Full year's Membership company logo branding in association with ISES on online and offline materials
- You will also receive priority consideration to join the Advisory Board &/OR Event Task Force positions



## 4 • BECOME A MEMBER



INTERNATIONAL  
**SEMICONDUCTOR**  
EXECUTIVE SUMMITS



MEMBERSHIP

Member

# JOIN TODAY

# \$5,000

\*Below is an example of membership cost savings when registering a ISES USA 2023 event pass:

- Member Rate per event: **\$1,497**
- Non-Member rate per event: **\$3,397**

Please click here to register online:

[WWW.ISESGLOBAL.COM/MEMBERSHIP/](http://WWW.ISESGLOBAL.COM/MEMBERSHIP/) 



### ISES MIDDLE EAST 2023

- DATE 22-23 February
- LOCATION Oman

### ISES USA 2023

- DATE 07-08 March
- LOCATION Phoenix, Arizona

### ISES TAIWAN 2023

- DATE 09-10 May 2023
- LOCATION Taipei

### ISES EU POWER 2023

- DATE 14-15 September
- LOCATION Italy

### ISES CHINA 2023

- DATE 17-18 October
- LOCATION China

### ISES SEA 2023

- DATE 7-8 November
- LOCATION Penang/Malaysia